

Title (en)
CONDUCTOR COUPLING ARRANGEMENT FOR COUPLING CONDUCTORS

Title (de)
LEITERBAHNKOPPLUNGSANORDNUNG ZUR KOPPLUNG VON LEITERN

Title (fr)
AGENCEMENT DE COUPLAGE DE CONDUCTEUR POUR LE COUPLAGE DE CONDUCTEURS

Publication
EP 3217470 A1 20170913 (EN)

Application
EP 16159209 A 20160308

Priority
EP 16159209 A 20160308

Abstract (en)
The present invention provides a conductor coupling arrangement 100 for coupling conductors 101, 102, comprising a first conductor 101, and a second conductor 102, wherein a protrusion 103, formed of conductive material on the first conductor 101, extends essentially perpendicular to a longitudinal extension of the first conductor 101, and wherein at least one coupling surface 103a of the protrusion 103 is separated from a coupling portion 104 of the second conductor 102 by at least a dielectric material 105, forming a capacitive coupling between the first conductor 101 and the second conductor 102.

IPC 8 full level
H01P 5/02 (2006.01); **H01R 24/38** (2011.01); **H01P 5/08** (2006.01); **H01R 13/66** (2006.01)

CPC (source: EP)
H01P 5/028 (2013.01); **H01P 5/08** (2013.01)

Citation (applicant)
• EP 0901181 A2 19990310 - HUGHES ELECTRONICS CORP [US]
• US 7629944 B2 20091208 - LENART GREGOR [SE], et al
• US 2012256794 A1 20121011 - VEIHL JONATHON C [US], et al

Citation (search report)
• [XYI] US 5156559 A 19921020 - SOMMER ERNST [DE], et al
• [YDA] US 2012256794 A1 20121011 - VEIHL JONATHON C [US], et al
• [XA] "Method for Implementing an AC Capacitively-Coupled Interconnect Using Coaxial PTH Vias in Organic Packages", IP.COM JOURNAL, IP.COM INC., WEST HENRIETTA, NY, US, 17 June 2010 (2010-06-17), XP013138699, ISSN: 1533-0001

Designated contracting state (EPC)
AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

Designated extension state (EPC)
BA ME

DOCDB simple family (publication)
EP 3217470 A1 20170913; EP 3217470 B1 20191016; CN 108780959 A 20181109; CN 108780959 B 20210226; WO 2017152837 A1 20170914

DOCDB simple family (application)
EP 16159209 A 20160308; CN 2017075945 W 20170308; CN 201780016453 A 20170308